

# **OPTIGA™ Trust M**

**Product Version: V3** 

### **About this document**

### **Scope and purpose**

The scope of this document is to provide the certificates to be considered while integrating the OPTIGA™ Trust M solution.

### **Intended audience**

This document addresses the audience: Customers, solution providers and system integrators.



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# Abbreviations



# 1 Abbreviations

### Table 1 Abbreviations

Abbreviation	Definition
CA	Certificate Authority
PKI	Public Key Infrastructure
NIST	National Institute of Standards and Technology





# 2 References

None

### **Infineon Test Certificates**



#### **Infineon Test Certificates** 3

The Infineon test certificates include the Infineon Test CA certificate and Infineon End Device Test certificate as shown in PKI hierarchy.

Note: Engineering Samples come with Test Certificates in Security Chip and Test CA on local host platform. These are not meant to be used for final product. Please use productive samples and productive CA for final product rollout.

The Infineon End Device Certificate is in default loaded in OPTIGA™ Trust M security chip Engineering samples. The Infineon Test CA is to be integrated to respective Host platform to perform device authentication.

#### **PKI Hierarchy for Test Certificates** 3.1

The PKI hierarchy of the OPTIGA™ Trust M Test certificates is as given below.

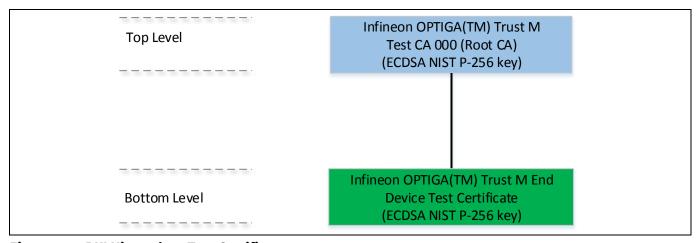


Figure 1 **PKI Hierarchy - Test Certificates** 





# 3.2 Infineon Test CA Certificate

The details of the Infineon Test CA are given below.

 Table 2
 Infineon Test CA Certificate

Type of Data										D	ata	in I	Hex								
Certificate Data	30	82	02	5F	30	82	02	05	A0	03	02	01	02	02	09	00					
Jeremeate Bata	FB	E1	CA	1A	90	F5	20	64	30	0A	06	08	2A	86	48	CE					
	3D	04	03	02	30	77	31	0B	30	09	06	03	55	04	06	13					
	02	44	45	31	21	30	1F	06	03	55	04	0A	0C	18	49	6E					
	66	69	6E	65	6F	6E	20	54	65	63	68	6E	6F	6C	6F	67					
												03									
												31				06					
												65				4 F					
		54										72									
												30									
												35									
												33 45									
												45 6E									
												73									
												50									
												04									
												49				54					
												54									
												07				CE					
												01				00					
	04	1в	51	FD	AC	28	A5	BD	0В	39	57	41	Α7	00	6E	23					
	64	F8	D3	C4	08	С7	5C	ΑO	80	5E	35	F6	6E	9F	10	1F					
	25	8C	56	F6	21	33	D5	D9	45	2E	5F	Α7	70	29	EC	F9					
	99	вЗ	4A	73	Α5	9В	98	AA	96	F8	0A	35	37	0A	88	8E					
	67	АЗ	7A	30	78	30	12	06	03	55	1D	13	01	01	FF	04					
	08	30	06	01	01	FF	02	01	00	30	0B	06	03	55	1D	ΟF					
	04	04	03	02	02	04	30	1D	06	03	55	1D	ΟE	04	16	04					
												В0									
												23				16					
												23				E2					
												1D									
												14									
												00									
												95									
												5F 45									
												F1									
		В6		ДЭ	OF	шV	OA	OE	ΕЭ	טט	ZΑ	ГТ	шп	70	21	UA					
SHA1 Thumbprint	+			30	f2	94	05	b3	03	84	08	94	7b	e1	се	50	19	e1	6b	de	
Sign and Hash Algorithm																					
Public Key parameters	-																				
Public Key	04	F 4	п-	7 ~	00	7 C	D.D.	0.5	2.0		4 -	~ ¬	0.0	<b>C</b> -	0.0	<i>C</i> 1					
												A7									
												6E									
												70									
	B3	4 A	13	СА	98	98	AA	ソり	r.Q	UΑ	33	37	UΑ	88	σE	ю/					

### **Infineon Test Certificates**



# 3.3 Infineon End Device Test Certificate

The details of the Infineon End Device Test certificate are given in the below.

Note:

The Infineon end device certificate will be different in the OPTIGA<sup>m</sup> Trust M samples if personalized for the unique keys and certificates.

**Table 3** Infineon End Device Test Certificate

Certificate Field	Data in Hex																				
Certificate Data (In Hex)	30	82	01	DD	30	82	01	82	A0	03	02	01	02	02	03	10					
,	00	01	30	0A	06	08	2A	86	48	CE	ЗD	04	03	02	30	77					
												44									
												69									
												65									
												4 F									
	41											55 54									
	54											20									
	20											31				32					
												38									
												30									
	04	03	0C	11	49	6E	66	69	6E	65	6F	6E	20	49	6F	54					
	20	4E	6F	64	65	30	59	30	13	06	07	2A	86	48	CE	3D					
	02											07				04					
	5D											9D				4A					
												65				5D					
												10									
												05				07					
	A3											01									
	30											FF 30				53					
	1B											84									
												0E									
	06											0A									
	48											02									
	28	АЗ	EF	ΑE	18	ЗА	DE	0A	0В	49	32	1D	A2	C2	ΕO	CF					
	AF	4E	D6	F2	FF	80	57	1E	4E	50	EF	СЗ	0 D	5D	02	21					
	00	F6	В9	E4	74	07	91	В4	2C	99	4B	45	С8	07	F3	1D					
		BF	7В	54	73	3В	0E	63	E6	0C	11	ΟE	09	11	13	43					
	19																				
SHA1 Thumbprint	2d	e9	11	СС	92	1f	b3	ca	43	3a	20	3a	7a	47	4 d	3b	fa	93	39	45	
Sign and Hash Algorithm	SH	A25	6 E	CDS	Ą																
Public Key parameters	ECDSA NIST P-256																				
Public Key	04																				
r ublic Ney	5 D	F7	36	9A	8B	47	E8	61	A6	94	5C	9D	EC	18	EF	4A					
	6F	BE	55	1C	78	23	74	A6	06	29	D4	65	9В	81	C2	5D					
	9F	F5	1F	70	8A	4 D	3F	19	36	70	СЗ	10	51	DD	67	12					
-	DC	F2	В6	2A	8A	70	53	92	13	95	2D	05	D2	90	38	07					

**Revision History** 



# **Revision History**

# Major changes since the last revision

Page or Reference	Description of change
All	Revision 0.50, Initial version
All	Revision 3.00, ES Release

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**Document reference** 

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